



# Material Composition Declaration

## EPC2014C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2/6/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	2.9085	88.5849	90.8797	885849
	Silicon oxide	7631-86-9	0.0101	0.3070		3070
	Silicon nitride	12033-89-5	0.0037	0.1114		1114
	Gallium nitride	25617-97-4	0.0134	0.4076		4076
	Aluminum	7429-90-5	0.0223	0.6805		6805
	Aluminum nitride	24304-00-5	0.0029	0.0868		868
	Titanium	7440-32-6	0.0007	0.0220		220
	Titanium nitride	25583-20-4	0.0030	0.0918		918
	Copper	7440-50-8	0.0004	0.0114		114
	Tungsten	7440-33-7	0.0007	0.0213		213
	Polyimide		0.0182	0.5551	5551	
Under Bump Metal	Titanium	7440-32-6	0.0005	0.0160	0.0797	160
	Copper	7440-50-8	0.0021	0.0637		637
Solder Bump	Copper	7440-50-8	0.0261	0.7962	9.0406	7962
	Nickel	7440-02-0	0.0156	0.4749		4749
	Tin	7440-31-5	0.2505	7.6296		76296
	Silver	7440-22-4	0.0046	0.1399		1399
Sum in total:			3.2832	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.